

0083-0865-2



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF : :

Masashi GOTOH, et al. : EXAMINER: CUNEO, K.

SERIAL NO.: 09/119,626 : :

CPA FILED: January 29, 2001 : GROUP ART UNIT: 2841

FOR: CIRCUIT BOARD HAVING :  
BONDING AREAS TO BE  
JOINED WITH BUMPS BY  
ULTRASONIC BONDING

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated March 13, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

Claim 13 is amended as follows:

13. (Once Amended) A circuit board comprising:

a main body; and

*et*  
a conductive layer provided on said main body, said conductive layer having  
conductive pattern, said conductive pattern having:

a plurality of bonding areas to where a plurality of bumps of a chip  
element are simultaneously joined by ultrasonic bonding; and

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